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(12) **United States Design Patent** (10) **Patent No.:** **US D823,270 S**
Nasu et al. (45) **Date of Patent:** **** Jul. 17, 2018**

(54) **SEMICONDUCTOR DEVICE**

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(**) Term: **15 Years**

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(52) **U.S. Cl.**
USPC **D13/182**

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361/679.01, 713, 728, 736, 760, 761, 772,
361/775, 783, 820; 174/250, 253;
438/15, 25, 26, 51, 55, 63, 64, 106
CPC . H01L 21/00; H01L 2224/42; H01L 2224/43;
H01L 2021/00; H01L 2021/02; H01L
2021/04; H01L 21/4814; H01L 21/4846;
H01L 21/4871; H01L 21/67144; H01L
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2924/1905; H01L 2224/08054; H01L
23/58; H05B 41/14; H02B 6/4201; G02B
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G02B 6/4262; G02B 6/428; G02B
6/4281; H05K 1/14; H05K 1/141; H05K
1/142; H05K 1/144; H05K 1/18; H05K
1/181; H05K 1/182; H05K 1/026

See application file for complete search history.

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(57) **CLAIM**

The ornamental design for a semiconductor device, as shown and described.

DESCRIPTION

FIG. 1 is a perspective view of a semiconductor device showing our new design;

FIG. 2 is a front view thereof, the rear view being a mirror image of FIG. 2;

FIG. 3 is a top plan view thereof;

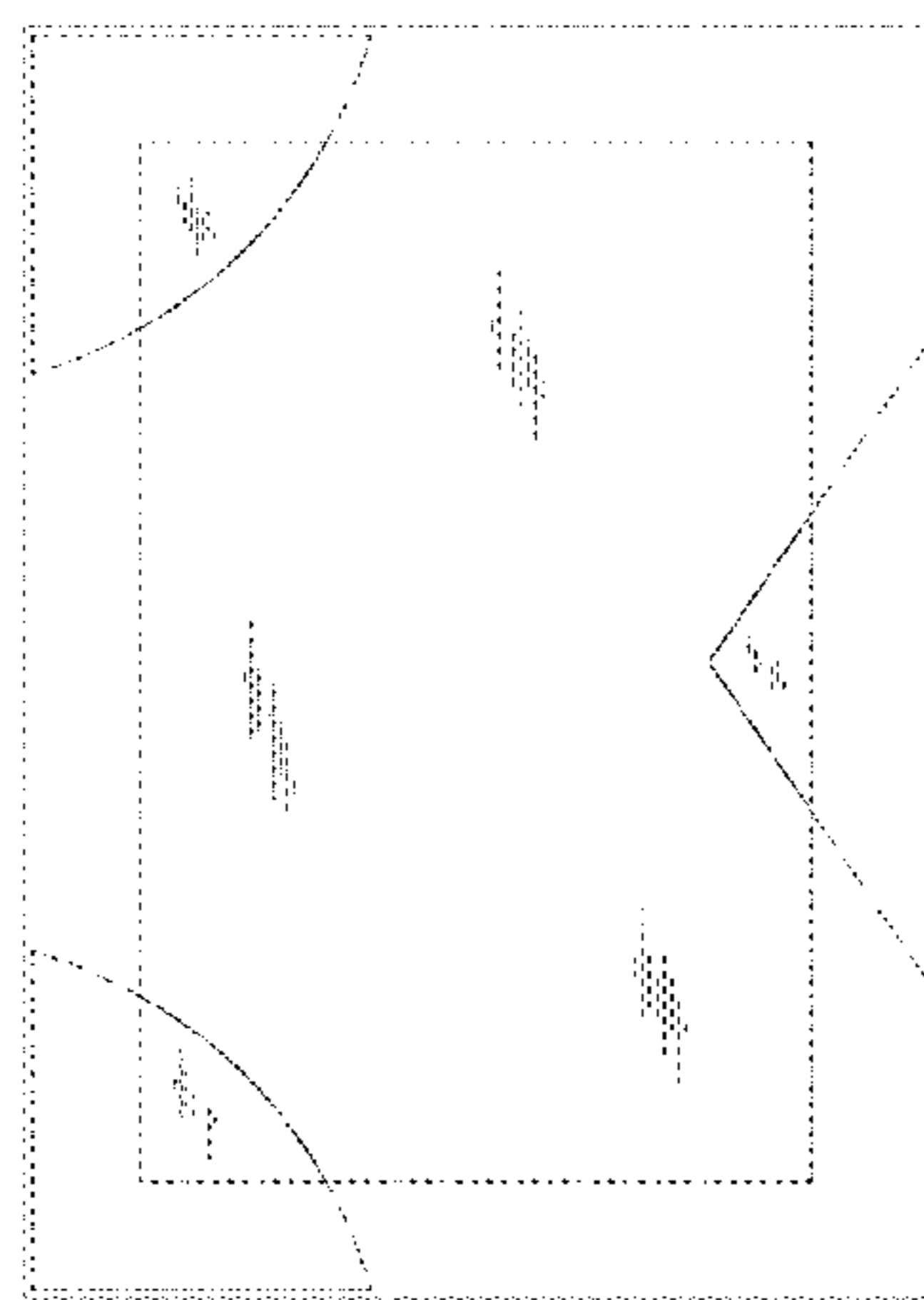
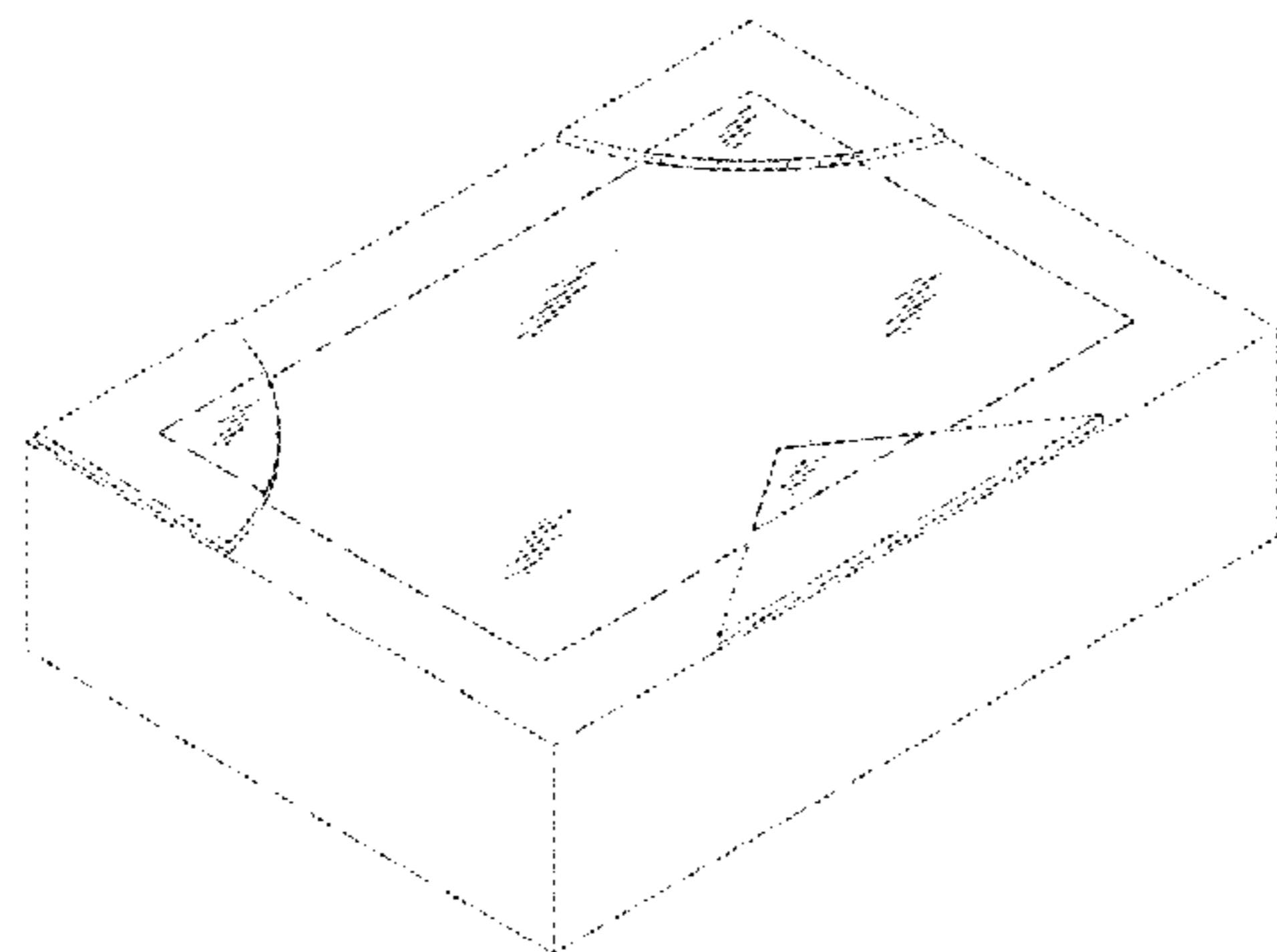
FIG. 4 is a bottom plan view thereof;

FIG. 5 is a right side view thereof; and,

FIG. 6 is a left side view thereof.

The features shown in broken lines in the drawings depict portions of the article that form no part of the claimed design. The dash-dotted lines denote the boundary of the claim and form no part of the claimed design.

1 Claim, 5 Drawing Sheets



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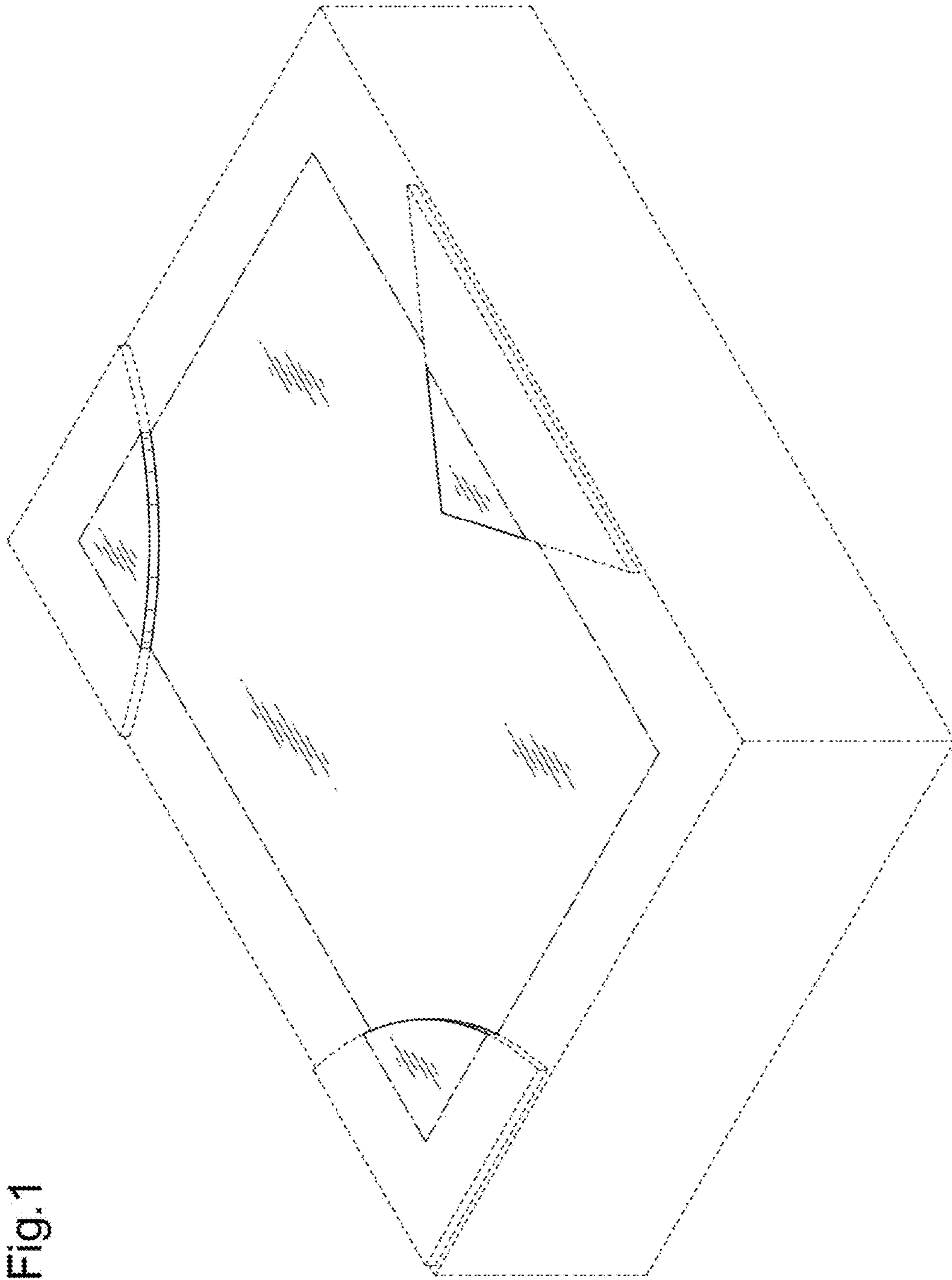


Fig. 1

Fig.2



Fig.3

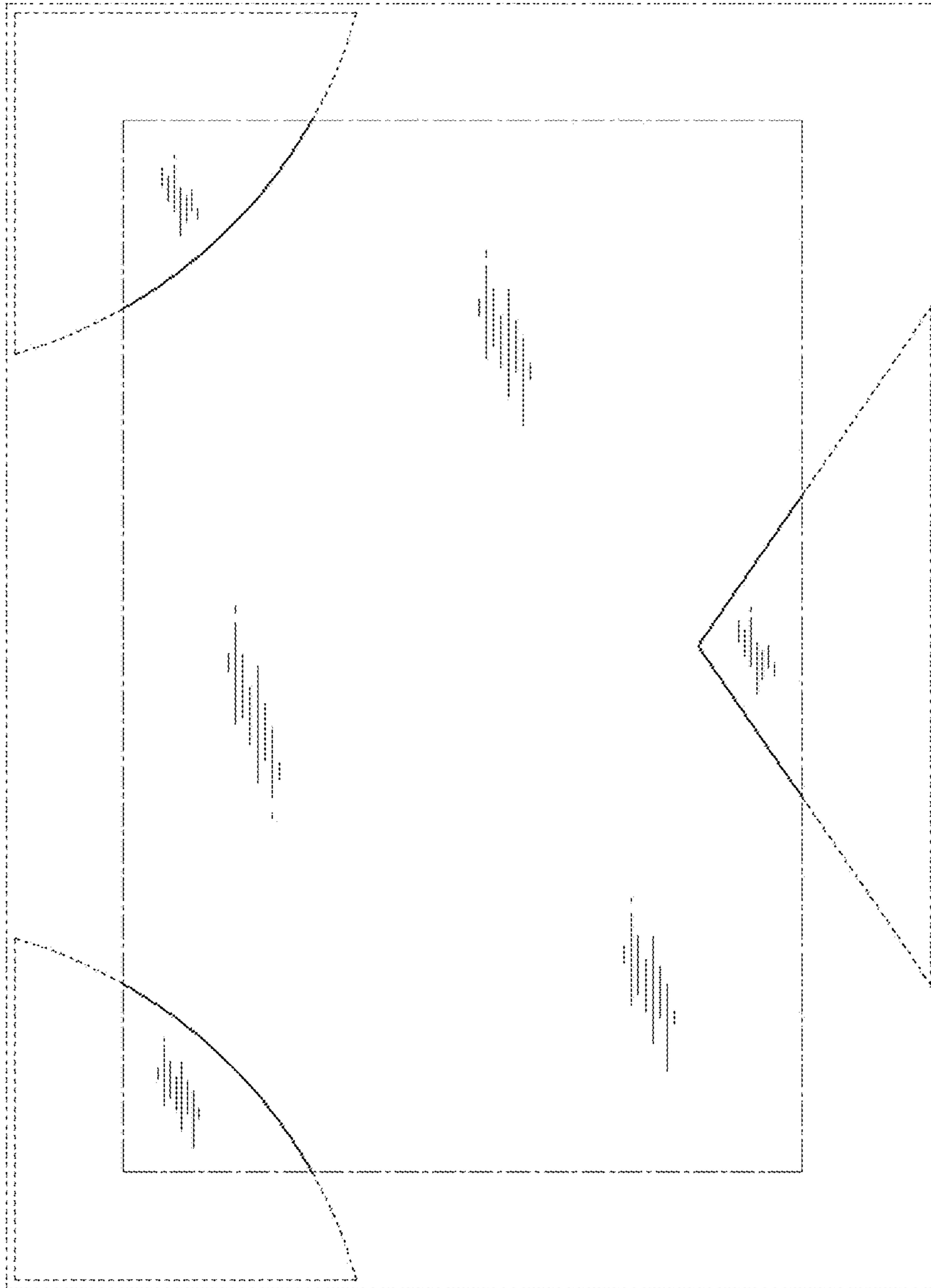


Fig.4

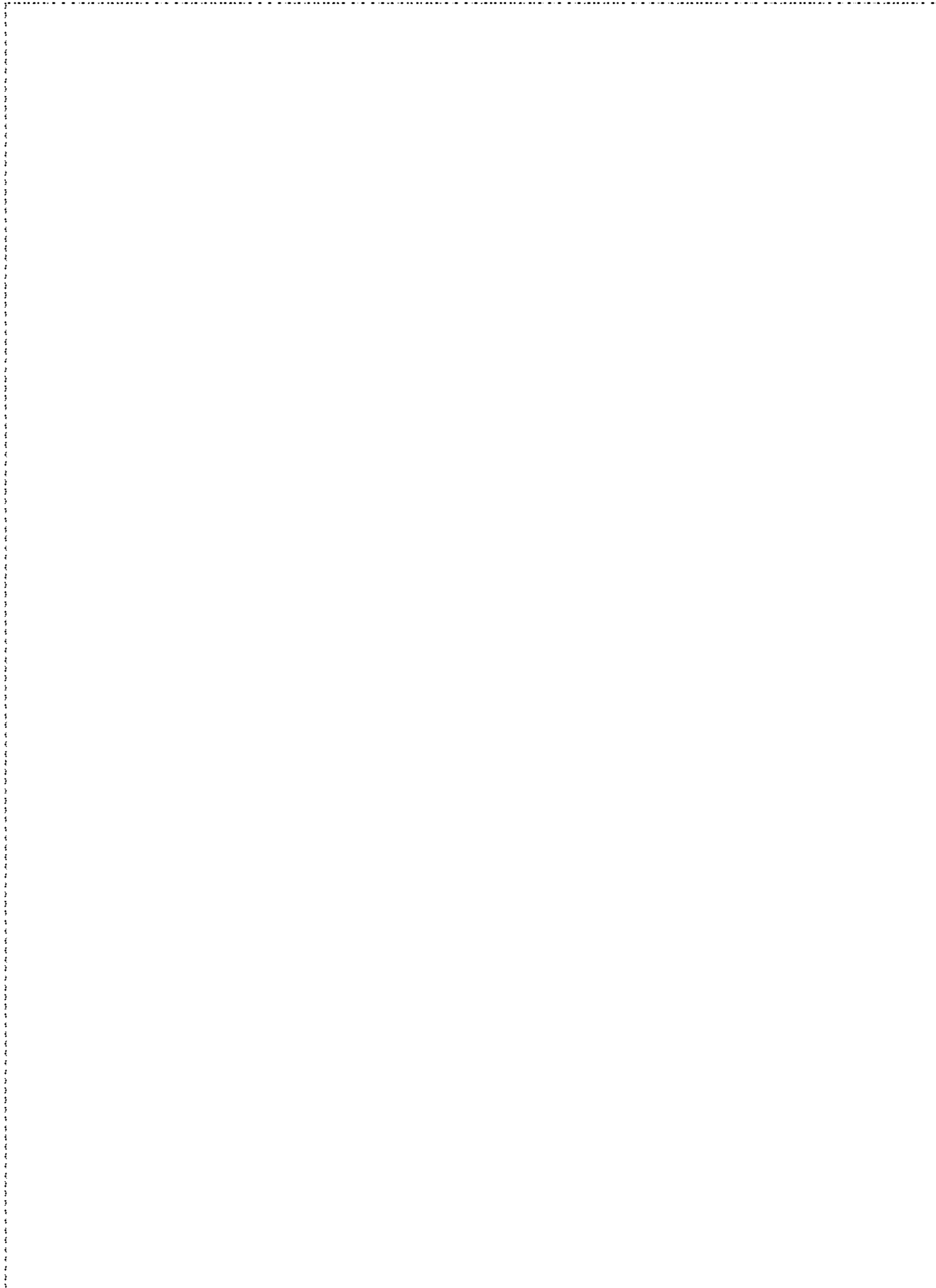


Fig.5

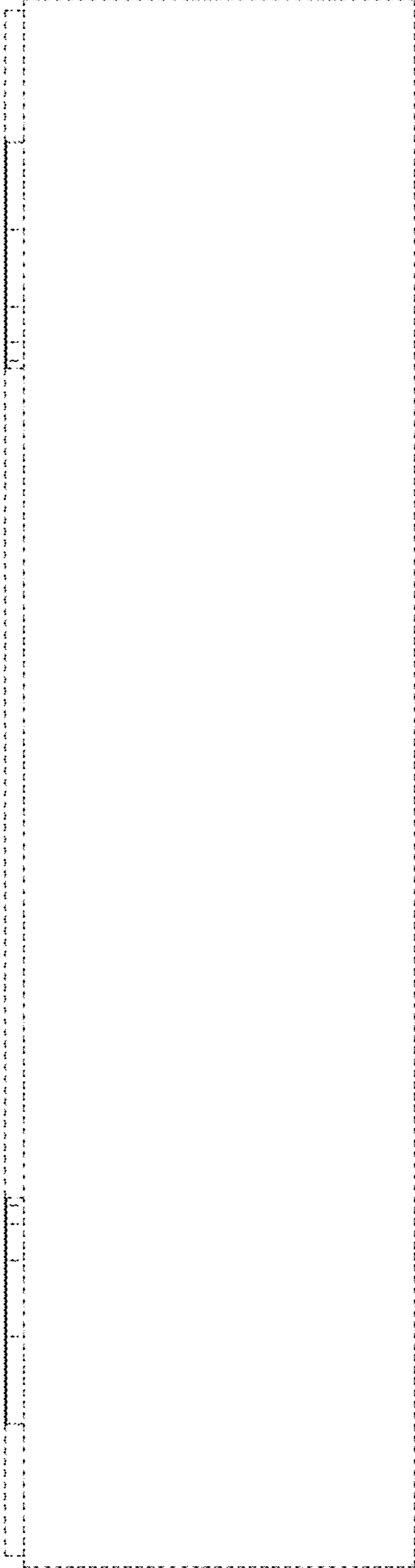


Fig.6

